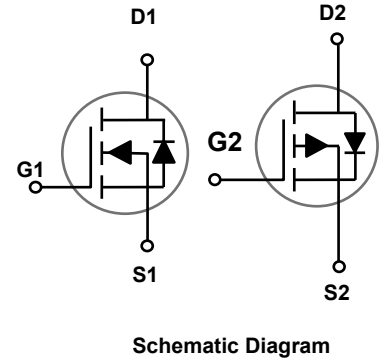
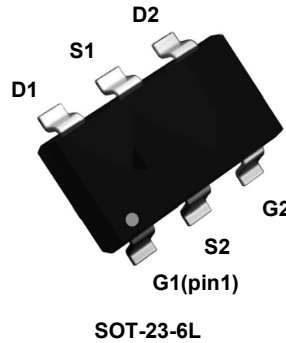


### Main Product Characteristics

Polarity	N-Ch	P-Ch
$V_{DSS}$	20V	-20V
$R_{DS(ON)(Max.)}$	40m $\Omega$	100m $\Omega$
$I_D$	3.8A	-2.5A



### Features and Benefits

- Advanced MOSFET process technology
- Ideal for notebook, load switch, networking and hand-held devices
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The SSF2116 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	20	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	$\pm 10$	V
Drain Current - Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	3.8	-2.5	A
Drain Current - Continuous ( $T_C=100^\circ\text{C}$ )		2.3	-1.5	A
Drain Current - Pulsed <sup>1</sup>	$I_{DM}$	15.2	-10	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	1.25	1.25	W
Power Dissipation - Derate above $25^\circ\text{C}$		0.01	0.01	W/ $^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150		$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55 to +150		$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$

### N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	-	0.02	-	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=20V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS}=16V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=3A$	-	30	40	m $\Omega$
		$V_{GS}=2.5V, I_D=2A$	-	42	55	
		$V_{GS}=1.8V, I_D=1.5A$	-	55	70	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	0.3	0.6	1	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-2	-	mV/ $^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=2A$	-	4.4	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2, 3</sup>	$Q_g$	$V_{DS}=10V, V_{GS}=4.5V, I_D=3A$	-	5.8	10	nC
Gate-Source Charge <sup>2, 3</sup>	$Q_{gs}$		-	0.6	1.5	
Gate-Drain Charge <sup>2, 3</sup>	$Q_{gd}$		-	1.5	3	
Turn-On Delay Time <sup>2, 3</sup>	$T_{d(on)}$	$V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega, I_D=1A$	-	2.9	6	nS
Rise Time <sup>2, 3</sup>	$T_r$		-	8.4	16	
Turn-Off Delay Time <sup>2, 3</sup>	$T_{d(off)}$		-	19.2	38	
Fall Time <sup>2, 3</sup>	$T_f$		-	5.6	12	
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, F=1\text{MHz}$	-	315	600	pF
Output Capacitance	$C_{oss}$		-	50	80	
Reverse Transfer Capacitance	$C_{rss}$		-	40	60	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	3.8	A
Pulsed Source Current	$I_{SM}$		-	-	7.6	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	-	-	1	V

**Notes:**

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

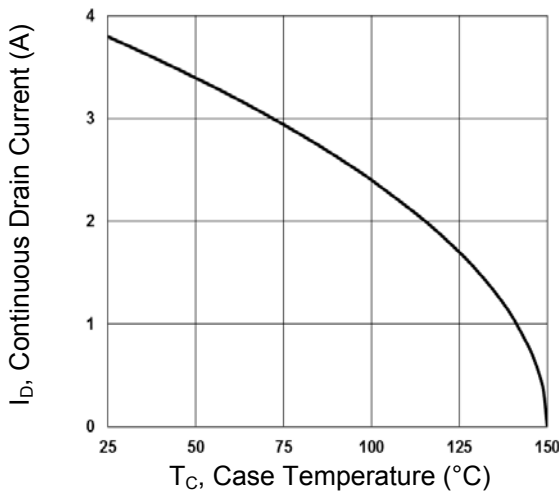
### P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	-	-0.01	-	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	-10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-3A$	-	82	100	m $\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	-	125	140	
		$V_{GS}=-1.8V, I_D=-1A$	-	197	230	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	3	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-1A$	-	2.2	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2, 3</sup>	$Q_g$	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-2A$	-	4.8	10	nC
Gate-Source Charge <sup>2, 3</sup>	$Q_{gs}$		-	0.5	1	
Gate-Drain Charge <sup>2, 3</sup>	$Q_{gd}$		-	1.9	4	
Turn-On Delay Time <sup>2, 3</sup>	$T_{d(on)}$	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=25\Omega, I_D=-1A$	-	3.5	7	nS
Rise Time <sup>2, 3</sup>	$T_r$		-	12.6	24	
Turn-Off Delay Time <sup>2, 3</sup>	$T_{d(off)}$		-	32.6	62	
Fall Time <sup>2, 3</sup>	$T_f$		-	8.4	16	
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$	-	350	510	pF
Output Capacitance	$C_{oss}$		-	65	95	
Reverse Transfer Capacitance	$C_{rss}$		-	50	75	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	-2.5	A
Pulsed Source Current	$I_{SM}$		-	-	-5	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	-	-	-1	V

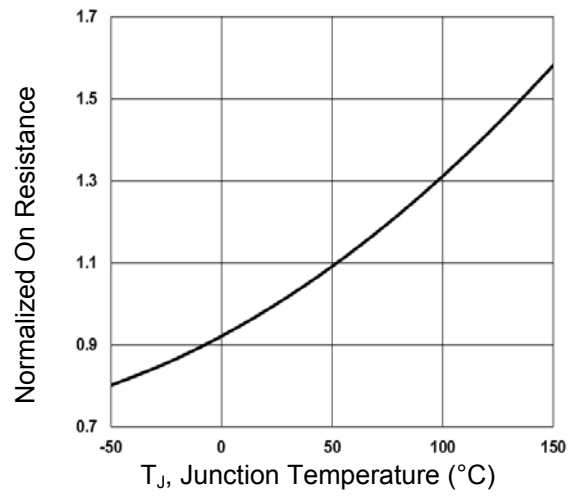
**Notes:**

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

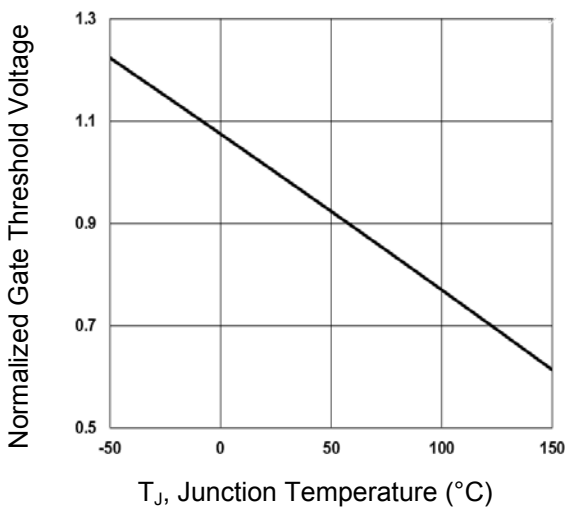
### N-Channel Typical Characteristic Curves



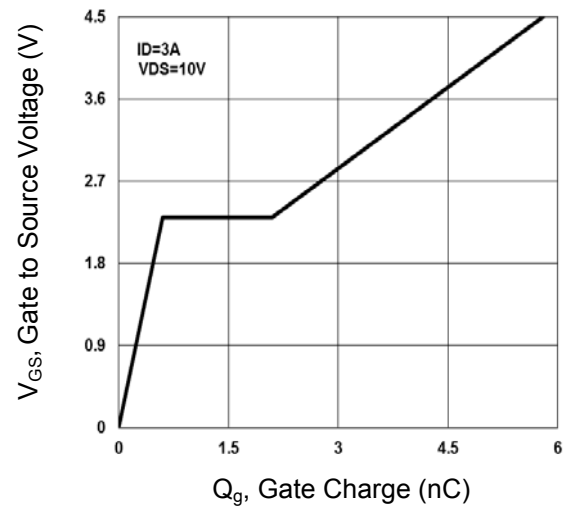
**Figure 1. Continuous Drain Current vs.  $T_C$**



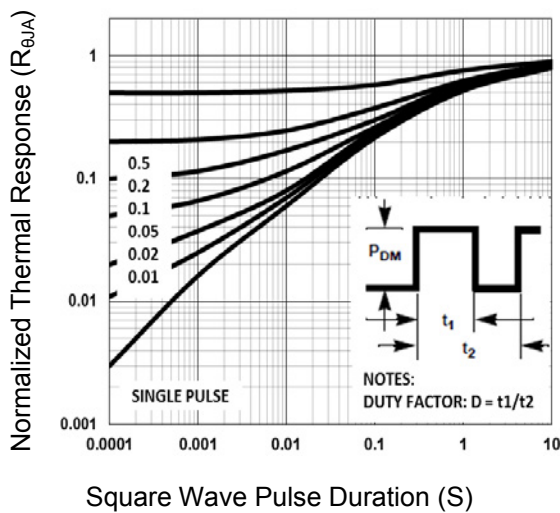
**Figure 2. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



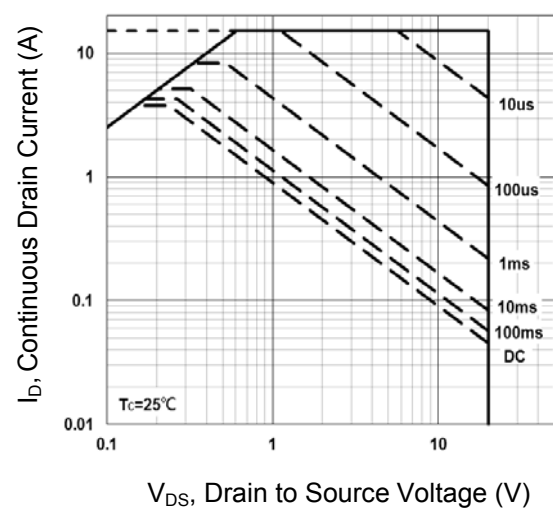
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**

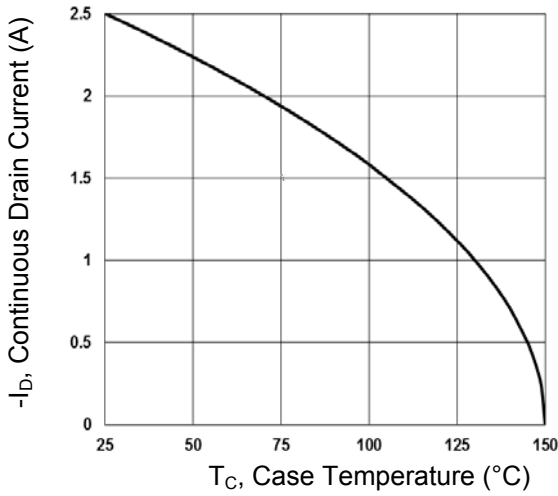


**Figure 5. Normalized Transient Impedance**

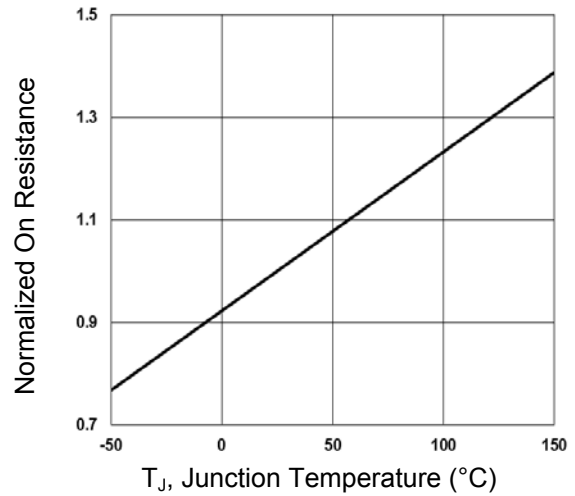


**Figure 6. Maximum Safe Operation Area**

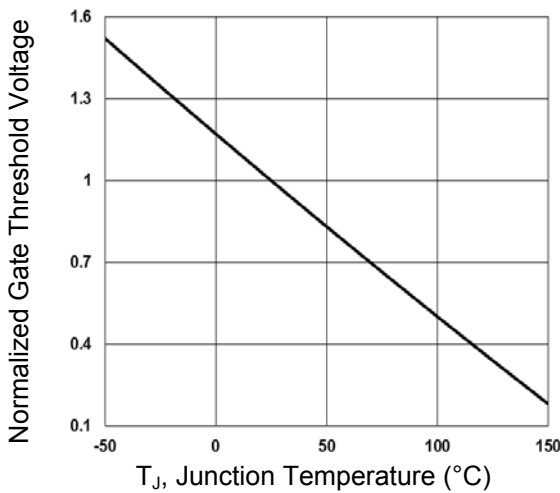
### P-Channel Typical Characteristic Curves



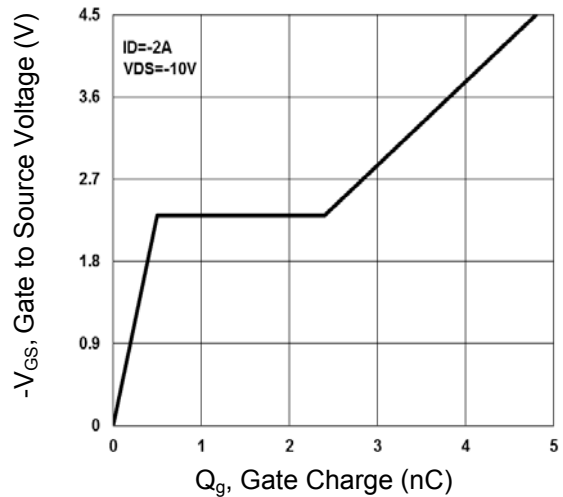
**Figure 7. Continuous Drain Current vs.  $T_c$**



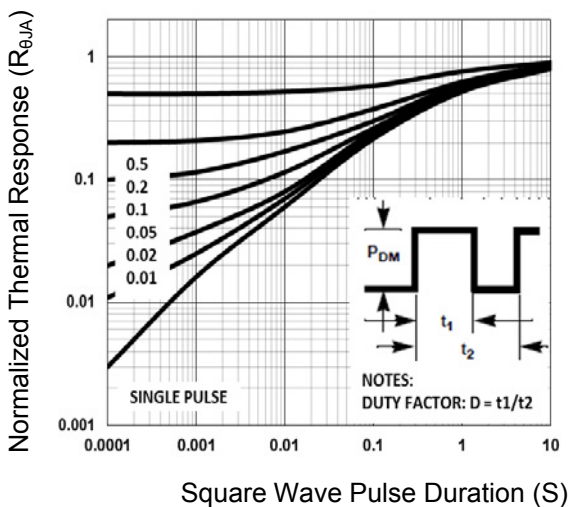
**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_j$**



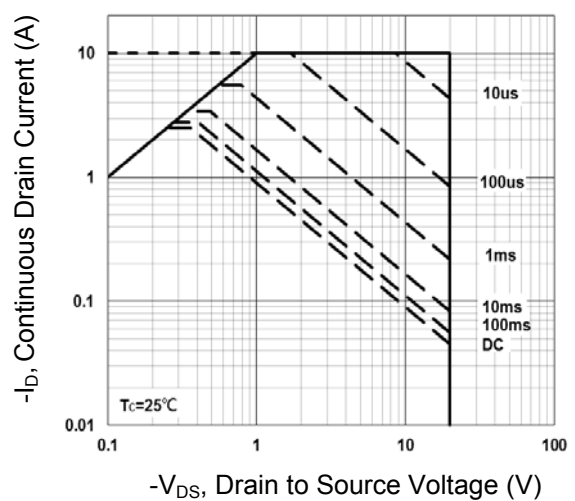
**Figure 9. Normalized  $V_{th}$  vs.  $T_j$**



**Figure 10. Gate Charge Waveform**

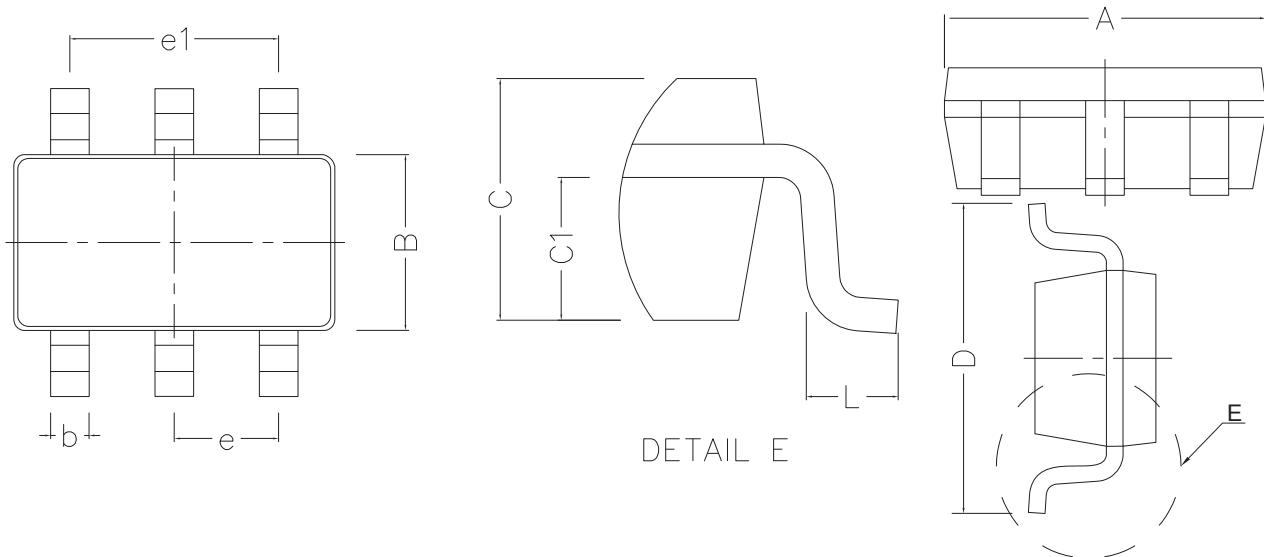


**Figure 11. Normalized Transient Impedance**



**Figure 12. Maximum Safe Operation Area**

### Package Outline Dimensions (SOT-23-6L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.82	3.02	0.111	0.119
B	1.50	1.70	0.059	0.067
C	1.05	1.15	0.041	0.045
C1	0.60	0.70	0.024	0.028
D	2.65	2.95	0.104	0.116
L	0.30	0.60	0.012	0.024
b	0.28	0.42	0.011	0.017
e	0.95 TYP		0.037 TYP	
e1	1.90 TYP		0.075 TYP	

### Order Information

Device	Package	Marking Code	Packaging	SPQ
SSF2116	SOT-23-6L	c*(* varied by lots)	Tape & Reel	3,000 pcs / Reel